

# HybridPACK™ Drive G2 for Traction Inverter

Infineon Technologies AG

May 2024



# Infineon offers all components for Traction Inverters

## The one-stop shop for competitive application solutions



### Functional Safety

- > Complementing and interoperable chip set
- > ISO26262 compliance
- > Harmonized Documentation

### Traction Inverter

- > [Overview](#)
- > [Products](#)
- > [Documents](#)
- > [Videos](#)
- > [Training](#)
- > [Support](#)

### Products

- > [Microcontroller](#)
- > [Driver Stage](#)
- > [PMIC](#)
- > [CAN Transceiver](#)
- > [Memory](#)
- > [IGBT Modules / SiC Modules](#)
- > [Position Sensor](#)

### Microcontrollers

> AURIX™

### IFX product offering

- > Multi-core device
- > Safety & security
- > Scalable across xEV

### Power Supply

> OPTIREG™ PMIC

### IFX product offering

- > Functional Safety
- > OPTIREG™ PMIC
- > TLF35584 – for safety relevant applications

### Gate Driver

> EiceDRIVER™

### IFX product offering

- > Increase system efficiency and lifetime
- > Reduction of system cost

### Current sensors

> XENSIV™

### IFX product offering

- > AC current measurement
- > ADC interface
- > Standalone sensor

### Power Switches

> Modules, Discretes, Bare Dies

### IFX product offering

- > Broad product family
- > WBG: Si, SiC
- > High volume experience

### Current Sensor

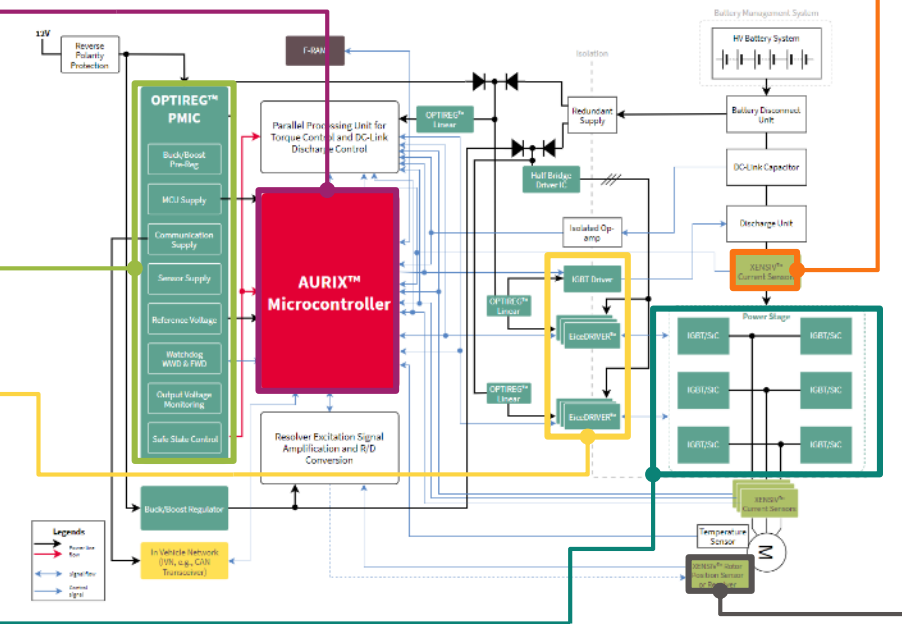
- > Highly accurate & core-less
- > Enables compact designs
- > Module from partner Swoboda in development

### Position sensors

> XENSIV™

### IFX product offering

- > Integrated end-of-shaft rotor position sensing solution
- > More compact design



# Target Application: Traction Inverter

## Infineon's latest development for Automotive Power Modules



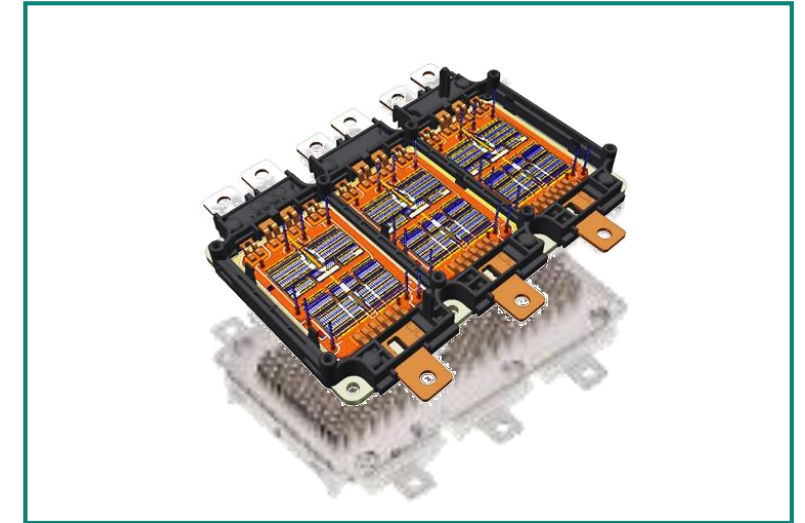
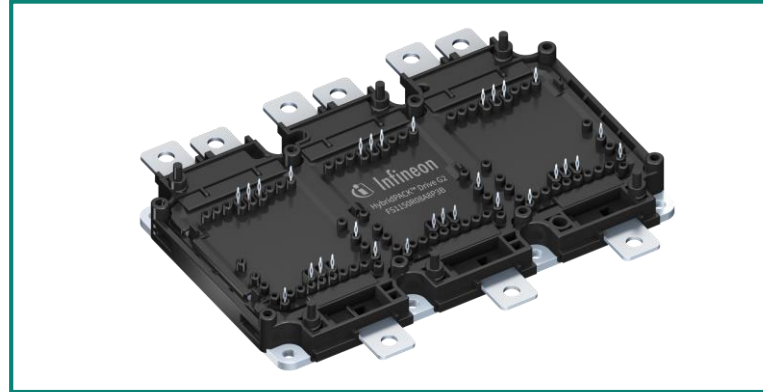
HybridPACK™ Drive G2  
Higher power density with Infineon's latest IGBT and SiC technologies



eMobility



Traction inverter



Motivation

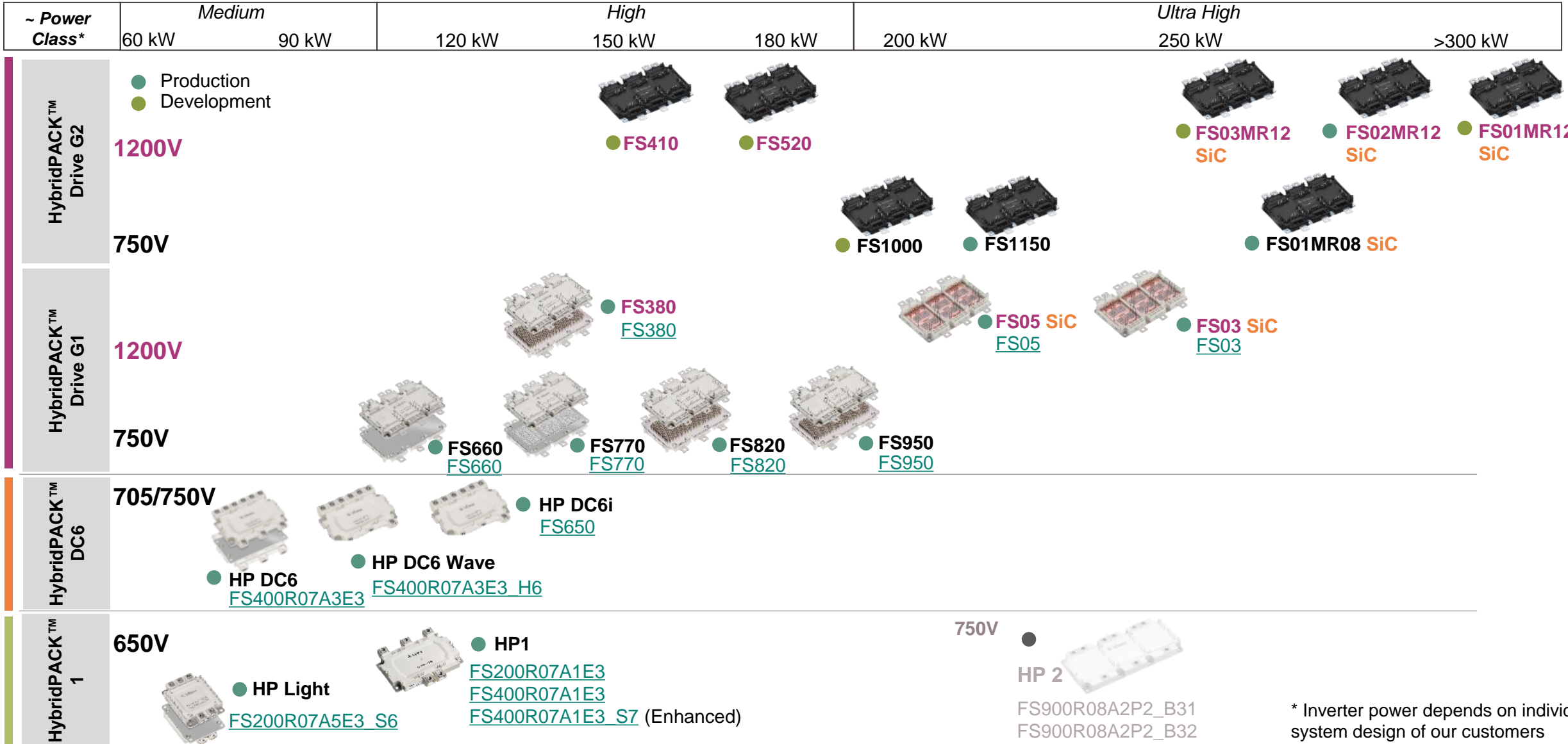
- A clear trend in the traction inverter application, globally, is the increased demand for efficiency and performance, which translates into higher inverter power, lower losses, reduced cooling effort and a better power to cost ratio.



Product description

- Incorporating Infineon's latest IGBT and SiC technologies (EDT3 and CoolSiC™ G2 options) and maximizing chip size inside the well established HybridPACK™ Drive form factor, the HybridPACK™ G2 offers higher power with a better power to cost ratio and benchmark power cycling capability compared to its first generation.

# HybridPACK™ product families cover the full performance spectrum



\* Inverter power depends on individual system design of our customers

# HybridPACK™ G2

## Power your inverter with most scalable portfolio across Si & SiC



Subject to change

	750 V	1200 V		
SiC G2	<p>1.1mΩ</p>  <p>FS01</p>	<p>2.9mΩ</p>  <p>FS03</p>	<p>2.2mΩ</p>  <p>FS02</p>	<p>1.5mΩ</p>  <p>FS01</p>
IGBT EDT3	<p>~ 750 A<sub>rms</sub></p>  <p>FS1000</p>	<p>~900 A<sub>rms</sub></p>  <p>FS1150</p>	<p>~ 315 A<sub>rms</sub></p>  <p>FS410</p>	<p>~395 A<sub>rms</sub></p>  <p>FS520</p>

■ SOP ■ Sample

# HybridPACK™ Drive G2 Si IGBT 1200V / 750V Portfolio Overview



Subject to change

## HybridPACK™ G2

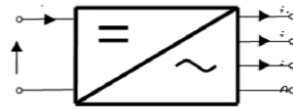
### Picture



### Timeline

	EES	ES	QS	SOP
<b>FS1000</b>	●	●	Q2/24	Q4/24
<b>FS1150</b>	●	●	Q1/24	Q2/24
<b>FS410</b>	●	●	Q3/24	Q3/24
<b>FS520</b>	●	●	Q2/24	Q2/24

### Key Applications



Traction Inverter

## Features

- New EDT3 750V and EDT(1) 1200V technologies with improved thermal stacks
- Long AC tabs optional, to enable current sensing
- Lower AC contact resistance and increased tabs thickness (1,5mm)
- Improved pin rivet ensuring high robustness over entire temperature range
- PinFin baseplate for direct cooling
- Die attach technology with sintering



## Portfolio Overview

Products	Voltage	Arms	Substrate Variant	AC Tab Thickness
FS1150	750	900	SiN (A8)	1.5mm
FS1000	750	750	Al <sub>2</sub> O <sub>3</sub> (A7)	1.0mm
FS520	1200	395	SiN (A8)	1.5mm
FS410	1200	315	Al <sub>2</sub> O <sub>3</sub> (A7)	1.0mm

## Customer Benefits

- High robustness over entire temperature range
- Supports continuous operating temperature @175°C and Peak@185°C (FS1150, FS1300)
- >900Arms continuous possible (Gen1 ~550 Arms)
- Improved thermal conductivity
- Increased durability especially in harsh environment



# HybridPACK™ Drive G2 SiC 1200V / 750V Portfolio Overview



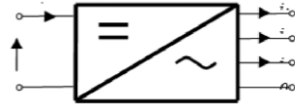
Subject to change

## HybridPACK™ G2

### Module



### Key Applications



### Traction Inverter

## Features

- ATV CoolSiC™ Trench MOSFET Gen2
- Enhanced Package (sintered, performance ceramic)
- PinFin baseplate for direct cooling
- Supports continuous operating temperature at 175°C
- Supports peak operating temperatures at 190°C
- Improved Pin Rivet. High robustness over entire temperature range
- Long AC tabs optional, to enable current sensing
- Lower AC contact resistance and lower tab temperature

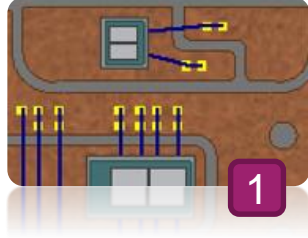
## Portfolio Overview

Products	Voltage	R <sub>DSon</sub> *	Status	ES	QS	SOP
FS01MR08	750V	1.1 mOhm	In production			Production
FS01MR12	1200V	1.5 mOhm	In development	●		Q4/2024
FS02MR12	1200V	2.2 mOhm	In production			Production
FS03MR12	1200V	2.9 mOhm	In development		●	Q3/2024

## Customer Benefits

- Superior gate oxide and cosmic ray reliability
- Enable scalable inverter platform development
- Reduces inverter losses by 2/3rd vs. state of the art IGBT solutions
- Operation up to 900Arms peak current with enhanced products

# HybridPACK™ Drive G2 package enhancements



**Sintered:**

- Temperature sensor
- Automotive Si/SiC  
1200 V / 750 V various population options

1



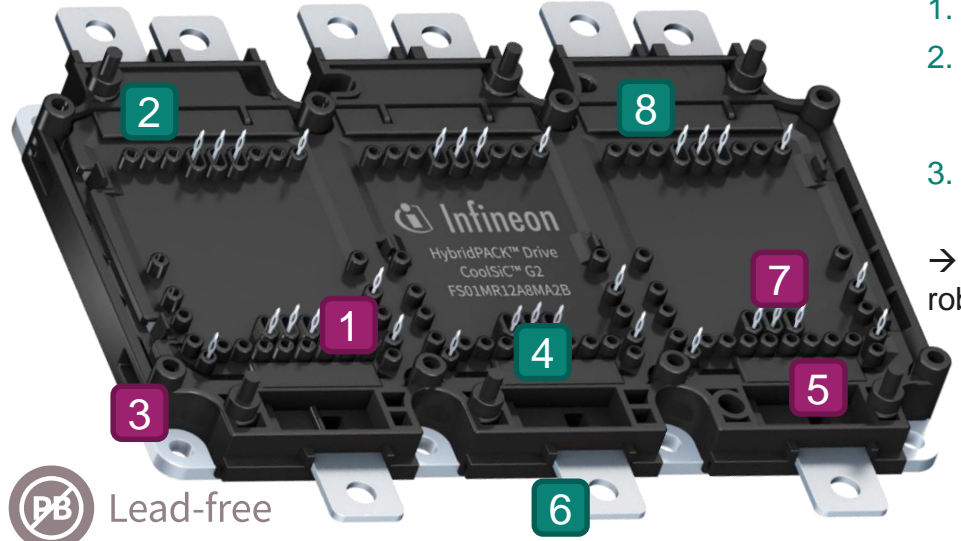
**6x Heat stake Dome. Reduced system BOM.** More effective PCB area.  
Backup Ejet screws are also available.

2

HPD Si & SiC G1/G2  
Well known PinFin Baseplate

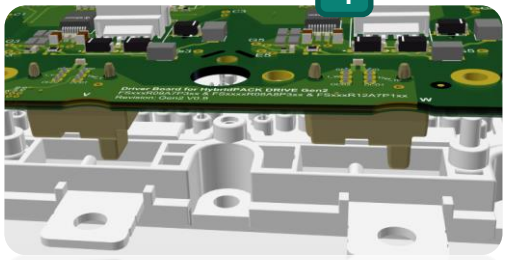


3

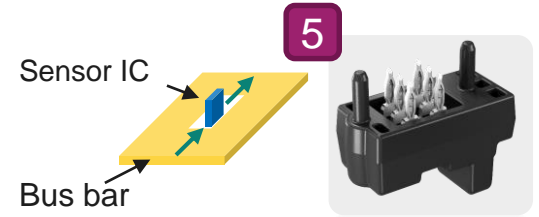


**Lead-free**

Sensor Module: 100% vertical mounting. No core. High accuracy. One Sensor fits all Drive G2 (IGBT and SiC MOSFET).



4



Tab slot to enable differential HALL sensors & current sensor from Swoboda-IFX with core-less sensing technology

5

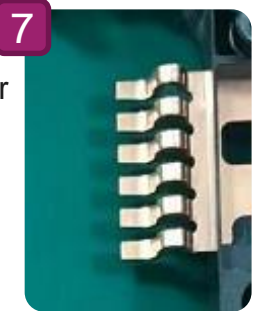
## Enhanced Robustness

- G2 Pin Rivet Connection
  - Sintered die attach  
**Further improvement of Power Cycling capability by factor 5**
  - Enhanced bond wire technology
- Significant achievement in robustness (TST, PCB, Pcsec)



8

Lower AC contact resistance and lower tab temperature. Continuous **currents up to 900 Arms** with enhanced products



7



Short and Long AC Tabs.  
Long tab for simultaneous LEM & diff Hall testing

6

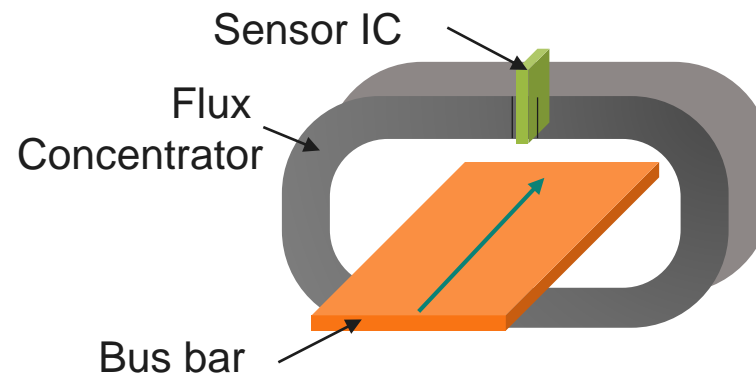


# Swoboda current sensor module scalable for complete HybridPACK™ Drive G2 portfolio



## Easy platform migration

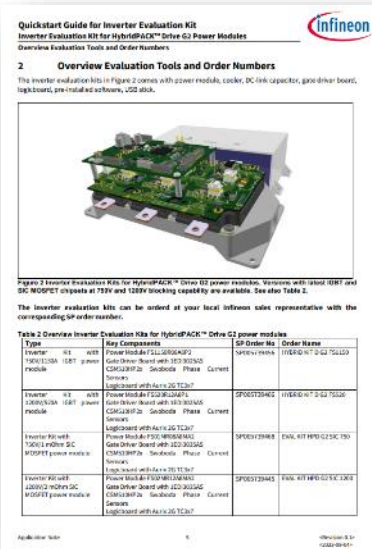
- Scalability cross whole HybridPACK™ Drive G2 portfolio
- Easy migration for preferred power segments



## Less cost & complexity

- Eliminate long tab
- No magnetic concentrator
- Reduce assembly time

# HybridPACK™ Drive G2 Inverter Evaluation Kit



Power Module	Driver	Sensor	Order code
IGBT 750V 1150A FS1150R08A8P3	1EDI3025AS	Swoboda CSM510HP2x	SP005739456 EV INV HPD2 SI FS1150 08
IGBT 1200V/520A FS520R12A8P1	1EDI3025AS	Swoboda CSM510HP2x	SP006038374 EV INV HPD2 SI FS520 12
SiC 750V/1 mOhm FS01MR08A8MA2	1EDI3035AS	Swoboda CSM510HP2x	SP005739468 EV INV HPD2 SIC FS01 08
SiC 1200V/2 mOhm FS02MR12A8MA2	1EDI3035AS	Swoboda CSM510HP2x	SP006056146 EV INV HPD2 SIC FS02 12

The inverter evaluation kits comes with two boards: power board & logic board.

- power board includes 1)power module 2) cooler 3)DC-link capacitor 4)gate driver
- logic board includes AURIX 2G TC3x7, pre-installed software, USB stick

# Infineon offers the most scalable portfolio in a single footprint for traction inverter application

HybridPACK™ Drive package was invented by Infineon and with a track record of almost 8.5 units sold since 2017, it is Infineon's market leading power module family for electric vehicles

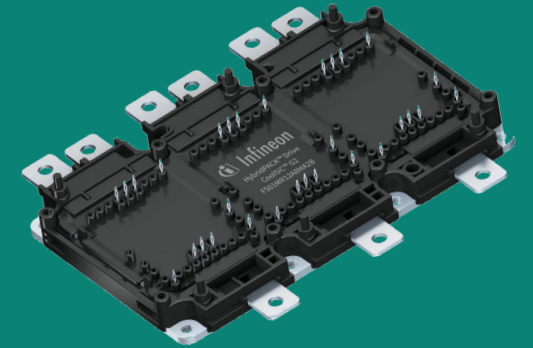
Market  
success

HybridPACK™ Drive G2 offers several package enhancements such as Rivet, Heat stake Domes, PinFin Baseplate, phase current sensors modules, and much more

G2  
innovation

Infineon is the one-stop shop for Traction Inverters components. HybridPACK™ Drive G2 offers a seamless connection with EiceDRIVER™ and XENSIV™ current sensor

System  
solution



## Summary

